

**ABSTRACT OF THE DISCLOSURE**

The invention relates to a soldering material comprising an alloy that in addition to Sn (tin) as the major constituent, comprises 10 wt.% or less Ag (silver), 10 wt.% or less Bi (bismuth), 10 wt.% or less Sb (antimony) and 3 wt.% or less Cu (copper). Furthermore, the invention relates to a soldering material comprising a plurality of soldering components with such alloy compositions and contents in the soldering material that on fusing the soldering components an alloy is formed that comprises Sn, Ag, Bi, Sb and Cu in the abovementioned alloy contents.